



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Manufacturing Info/ Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	Penica, John R	<b>Contact Title</b>	Mgr Environmental Engineering		
<b>Company Unique ID</b>	-	<b>Response Date</b>	2014-06-16	<b>Contact Email</b>	jrpenica@te.com				
<b>Contact Phone Number</b>	17175923266								
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	103308-1	<b>Amount</b>	1450.984858	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>		<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EURoHS-0508</b>	Product(s) does not meet EU RoHS requirements and is not under exemptions - true								
<b>ChinaRoHS-0508</b>	Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products - true								
<b>Manufacturing Information</b>									
<b>J-STD-020 MSL Rating</b>		<b>Max Total a Wave Time</b>		<b>Ramp Rate</b>		<b>Wave Additional Info</b>			
<b>Classification Temp</b>		<b>Max Wave Solder Time</b>	0.0	<b>Ramp Down Rate</b>		<b>Psi Rating Reflow</b>			
<b>Max Time Within 5</b>		<b>Psi Rating Wave</b>		<b>Package Designator</b>		<b>Size</b>	0.0		
<b>Time Above 217</b>		<b>Reflow Additional Info</b>		<b>Preheat Max Temp</b>		<b>Terminal Base Alloy</b>	NAC		
<b>Preheat Duration</b>		<b>bulk Solder Termination</b>	NAC	<b>Nbr or Reflow Cycles</b>		<b>Terminal Plating</b>	NAC		
<b>Preheat Min Temp</b>		<b>Nbr of Instances</b>	0	<b>Component Temp Spike</b>		<b>Shape</b>	NAC		
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Sub-Item	1	111662-1				1.0	1030.0	mg	
Material	2	PA66-GF25				1.0	1030.0	mg	
Substance	3	Benzenamine, reaction products with aniline hydrochloride and nitrobenzene	Supplier	101357-15-7	4.0	1.0	41.2	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	6.0	1.0	61.8	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	3.5	1.0	36.05	mg	
Substance	3	Poly[[imino(1,6-dioxo-1,6-hexanediy)]imino-1,6-hexanediy]]	Supplier	32131-17-2	61.5	1.0	633.45	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	25.0	1.0	257.5	mg	
Sub-Item	1	3-111573-6				10.0	42.0984858	mg	
Material	2	Nickel Plate				10.0	0.455547	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	10.0	9.1109E-4	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	10.0	4.5555E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	10.0	0.45418	mg	
Material	2	Brass Wire				10.0	41.365	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.07	10.0	0.0289555	mg	
Substance	3	Copper	Supplier	7440-50-8	71.5	10.0	29.57598	mg	

Substance	3	Beryllium	Supplier	7440-41-7	0.0010	10.0	4.1365E-4	mg	
Substance	3	Zinc	Supplier	7440-66-6	27.9975	10.0	11.58117	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.05	10.0	0.0206825	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	10.0	4.1365E-4	mg	
Substance	3	Iron	Supplier	7439-89-6	0.05	10.0	0.0206825	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	10.0	0.041365	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	10.0	0.0041365	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	10.0	0.0041365	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	10.0	0.0041365	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	10.0	2.0682E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	10.0	0.08273	mg	
Material	2	Gold Plate				10.0	0.0048178	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	10.0	1.44534E-5	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	10.0	0.00480335	mg	
Material	2	Gold Plate				10.0	0.072267	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	10.0	0.0720502	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	10.0	2.168E-4	mg	
Material	2	Tin-Lead Plate				10.0	0.200854	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	7.0	10.0	0.01405978	mg	
Substance	3	Tin	Supplier	7440-31-5	92.3	10.0	0.18539	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.7	10.0	0.00140598	mg	